2SD789

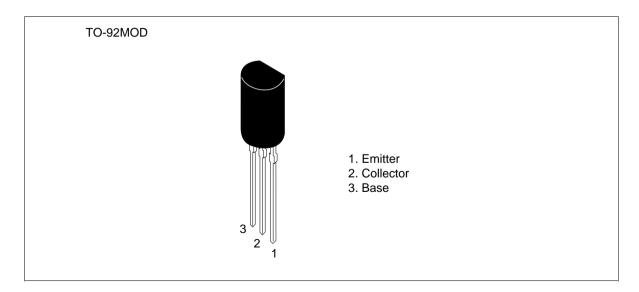
Silicon NPN Epitaxial

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Application

- Low frequency power amplifier
- Complementary pair with 2SB740

Outline





2SD789

Absolute Maximum Ratings (Ta = 25°C)

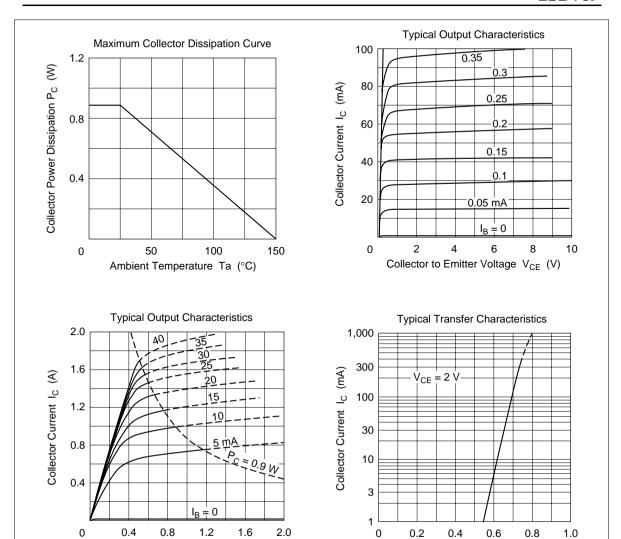
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	100	V
Collector to emitter voltage	V _{CEO}	50	V
Emitter to base voltage	V_{EBO}	6	V
Collector current	I _c	1	Α
Collector power dissipation	P _c	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	100	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\text{(BR)CEO}}$	50	_	_	V	$I_C = 1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	I _{CBO}	_	_	1	μΑ	$V_{CB} = 80 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	0.2	μΑ	$V_{EB} = 6 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	100	_	800		$V_{CE} = 2 \text{ V}, I_{C} = 0.1 \text{A}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.3	V	$I_{\rm C} = 1 \text{ A}, I_{\rm B} = 0.1 \text{ A}$
Gain bandwidth product	f⊤	_	100	_	MHz	$V_{CE} = 2 \text{ V}, I_{C} = 10 \text{ mA}$
Collector output capacitance	Cob	_	20	_	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{MHz}$

Note: 1. The 2SD789 is grouped by $h_{\rm FE}$ as follows.

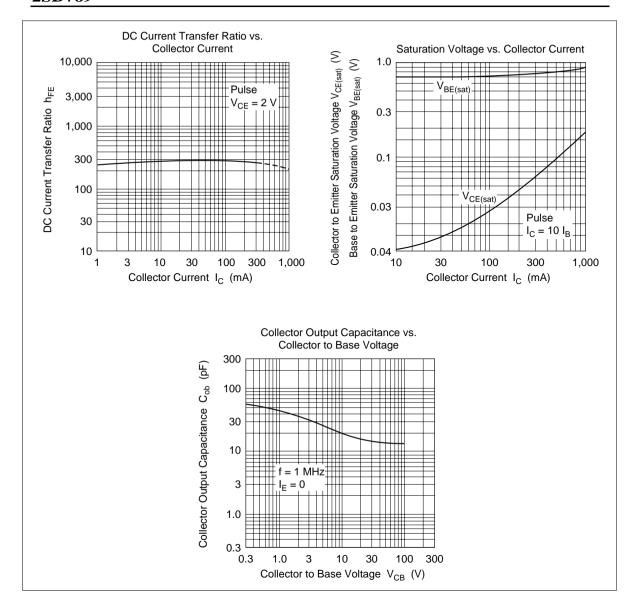
В	С	D	E
100 to 200	160 to 320	250 to 500	400 to 800



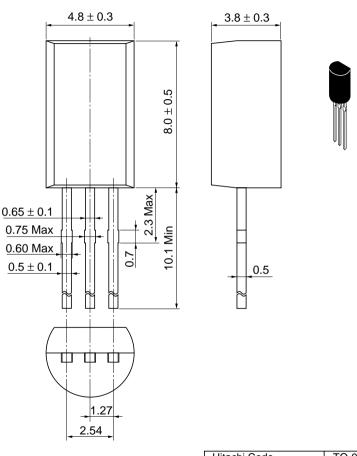
Collector to Emitter Voltage V_{CE} (V)

Base to Emitter Voltage V_{BE} (V)

2SD789



Unit: mm



Hitachi Code TO-92 Mod

JEDEC —

EIAJ Conforms

Weight (reference value) 0.35 g

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